IN THE CLAIMS

Please amend the claims as follows.

1. (Currently Amended) An apparatus for socketing and testing integrated circuits comprising:

an air machine that is operable to controllably provide a thermally-varying air flow; and

a housing comprising (i) a printed circuit board that is operable to receive a device under test, the printed circuit board comprising a leadless socket, and (ii) a controller that is operable to control testing of the received device under test;

wherein said air machine is associable with said housing to form an at least substantially air-tight chamber ensconcing the received device under test.

2. (Original) The apparatus as set forth in Claim 1 wherein said housing further comprises a power supply.

3. (Original) The apparatus as set forth in Claim 1 wherein said printed circuit board is circular shaped.

4. (Previously Presented) The apparatus as set forth in Claim 3 wherein said housing further comprises input/output (I/O) connectors that are placed circumferentially and symmetrically near the edge of the printed circuit board.

5. (Currently Amended) The apparatus as set forth in Claim 3 wherein ~~said printed circuit board comprises a~~ the leadless socket is self-registering.

6. (Currently Amended) The apparatus as set forth in Claim 5 wherein said leadless socket is operable to receive the device under test in [[the]] a center of the [[P]] printed circuit board.

7. (Currently Amended) A method of operating an apparatus for socketing and testing integrated circuits, said apparatus comprising an air machine and a housing, said housing comprising a printed circuit board and a controller, said method comprising the steps of:

(i) receiving a device under test at the printed circuit board, the printed circuit board comprising a leadless socket, and

(ii) associating said air machine with said housing to form an at least substantially air-tight chamber ensconcing the received device under test, the air machine operable to controllably provide a thermally-varying air flow.

8. (Original) The method as set forth in Claim 7 wherein said housing further comprises a power supply, and said method comprising the step of powering on the apparatus.

9. (Original) The method as set forth in Claim 7 wherein said printed circuit board is circular shaped, and said method comprising the step of controlling testing of the received device under test with said controller.

10. (Previously Presented) The method as set forth in Claim 9 wherein said housing further comprises input/output (I/O) connectors that are placed circumferentially and symmetrically near the edge of the printed circuit board.

11. (Currently Amended) The method as set forth in Claim 9 wherein ~~said printed circuit board comprises a~~ the leadless socket is self-registering.

12. (Currently Amended) The method as set forth in Claim 11 wherein said leadless socket is operable to receive the device under test in [[the]] a center of the [[P]] printed circuit board.

13. (Currently Amended) An apparatus for socketing and testing integrated circuits comprising:

an air machine that is operable to controllably provide a thermally-varying air flow; and

a housing comprising (i) a universal printed circuit board that is operable to receive a device under test, the printed circuit board comprising a leadless socket, (ii) a controller that is operable to control testing of the received device under test, and (iii) a power supply;

wherein said air machine is associable with said housing to form an at least substantially air-tight chamber ensconcing the received device under test.

14. (Original) The apparatus as set forth in Claim 13 wherein said power supply is a battery.

15. (Original) The apparatus as set forth in Claim 13 wherein said universal printed circuit board is circular shaped.

16. (Previously Presented) The apparatus as set forth in Claim 15 wherein said housing further comprises input/output (I/O) connectors that are placed circumferentially and symmetrically near the edge of the universal printed circuit board.

17. (Cancelled).

18. (Currently Amended) The apparatus as set forth in Claim [[17]] 13 wherein said leadless socket is operable to receive the device under test in [[the]] a center of the printed circuit board.

19. (Previously Presented) The apparatus as set forth in Claim 13 wherein the device under test is one of a radio frequency (RF) integrated circuit and a high-frequency integrated circuit.

20. (Currently Amended) The apparatus as set forth in Claim [[17]] 13 wherein said leadless socket is self-registering.

21. (New) The method of Claim 7, further comprising setting one or more desired temperatures and one or more desired cycle times for a test of the integrated circuits.